

Bi-directional ESD protection device, 18 V, 0.2 pF, 0201









Product description

This Infineon ESD (electrostatic discharge) protection device has a bi-directional and symmetric *I/V* characteristic and excellent clamping performance.

Feature list

- ESD / transient protection according to:
 - IEC61000-4-2 (ESD): ±18 kV (air) / ±18 kV (contact)
 - IEC61000-4-4 (EFT): ±2.5 kV / ±50 A (5/50 ns)
 - IEC61000-4-5 (Surge): ±3.5 A (8/20 μs)
- Bi-directional maximum working voltage: V_{WM} = ±18 V
- Line capacitance: $C_L = 0.2 \text{ pF at } f = 1 \text{ MHz}$
- Clamping voltage: $V_{cl} = 12.5 \text{ V}$ at $I_{TLP} = 16 \text{ A}$ with $R_{dyn} = 0.58 \Omega$
- Very low leakage current: I_L = 1 nA
- Small form factor SMD size 0201, low profile (0.58 x 0.28 x 0.15 mm³)







Potential applications

NFC, RF Antenna

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Device information

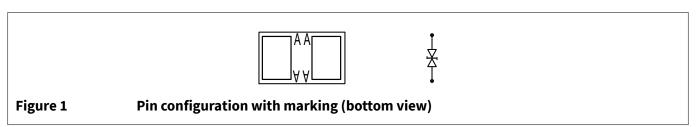


Table 1 Part information

Product name / Ordering code	Package	Pin configuration	Marking	Pieces / Reel
ESD144-B1-W0201/ESD144B1W0201E6327XTSA1	WLL-2-3	1 line, bi-directional	AA	15 k



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1 Absolute maximum ratings

Absolute maximum ratings 1

Table 2 Absolute maximum ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Va	lues	Unit	Note or test condition
		Min.	Max.		
Working voltage	V_{WM}	-18	+18	V	
ESD discharge voltage	V _{ESD} (contact)	-18	+18	kV	Discharge network:
	V _{ESD} (air)	-18	+18		$R = 330 \Omega, C = 150 \mathrm{pF}^{1)}$
Peak pulse power	P _{PK}	_	21	W	Stress pulse:
Peak pulse current	I _{PP}	-3.5	+3.5	А	8/20 μs current waveform ²⁾
Operating temperature	Top	-55	+125	°C	
Storage temperature	$T_{ m stg}$	-65	+150		

Attention: Stresses above the maximum values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings. Exceeding only one of these values may cause irreversible damage to the component.

¹ Based on IEC61000-4-2.

² Based on IEC61000-4-5.



2 Electrical characteristics

2 Electrical characteristics

Note: $T_A = 25$ °C, unless otherwise specified. Device is electrically symmetrical.

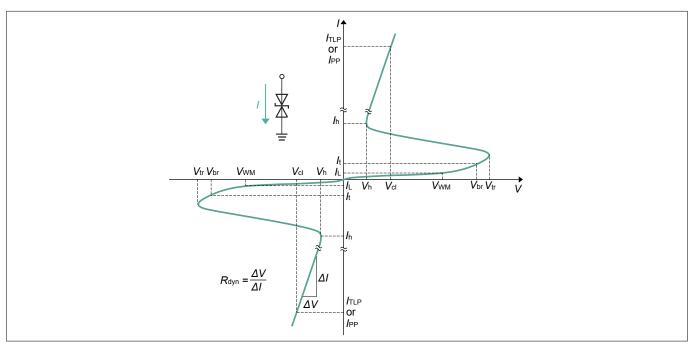


Figure 2 //V characteristic curve

Table 3 I/V characteristic parameters

Symbol	Parameter				
I_{h}	Holding current				
I _L	Leakage current				
I _{PP}	Peak pulse current, based on IEC61000-4-5				
I_{t}	Test current				
I _{TLP}	TLP current				
$R_{\rm dyn}$	Dynamic resistance				
$\overline{V_{br}}$	Breakdown voltage				
$\overline{V_{\rm cl}}$	Clamping voltage				
$\overline{V_{h}}$	Holding voltage				
$\overline{V_{t}}$	Test voltage				
$\overline{V_{tr}}$	Trigger voltage				
$\overline{V_{WM}}$	Maximum working voltage				

Note: For more detailed explanation of electrical parameters refer to [1]

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2 Electrical characteristics

Table 4 **DC** characteristics

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Breakdown voltage	$V_{ m br}$	18.5	22	28.5	V	$I_t = 1 \text{ mA}$
Holding voltage	V_{h}	_	1.9	_	V	$I = I_h$
Holding current	I _h	_	25	_		$V = V_h$
Leakage current	/ _L	_	1	50	nA	V _{WM} = 18 V

AC characteristics Table 5

Parameter	Symbol	Values		Unit	Note or test condition	
		Min.	Тур.	Max.		
Line capacitance	C_{L}	_	0.2	0.35	pF	V = 0 V, f = 1 MHz
		_	0.19	_		V = 0 V, f = 2.5 GHz
Series inductance	L _S	_	<1	-	nH	Extracted from S-parameters

Table 6 **Protection characteristics**

Parameter	Symbol		Values		Unit	Note or test condition
		Min.	Тур.	Max.		
Clamping voltage (TLP) 3) 4)	$V_{\rm cl}$	_	8	-	V	I _{TLP} = 8 A
		_	12.5	_		I _{TLP} = 16 A
Clamping voltage (8/20 µs) 5)		_	3	_		/ _{PP} = 1 A
		_	5	_		I _{PP} = 3 A
Dynamic resistance 3)	R _{dyn}	_	0.58	_	Ω	

³ TLP parameters: Z_0 = 50 Ω , t_p = 100 ns, t_r = 0.6 ns, averaging window 30-60 ns. Refer to application note AN210 [2]

⁴

 t_p = 8/20 μ s. Stress pulse based on IEC61000-4-5.



3 Typical characteristic diagrams

Note: $T_A = 25$ °C, unless otherwise specified.

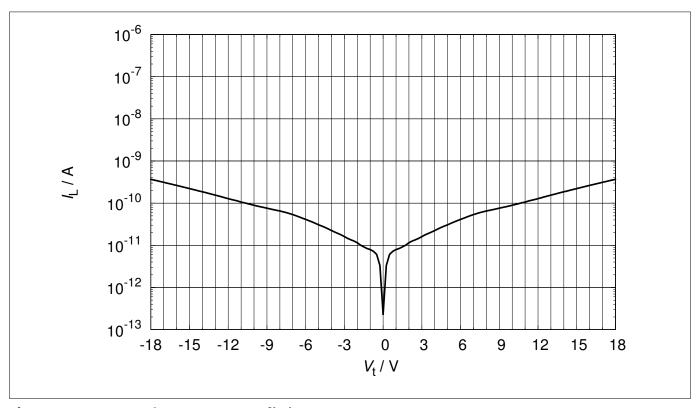


Figure 3 Leakage current: $I_L = f(V_t)$

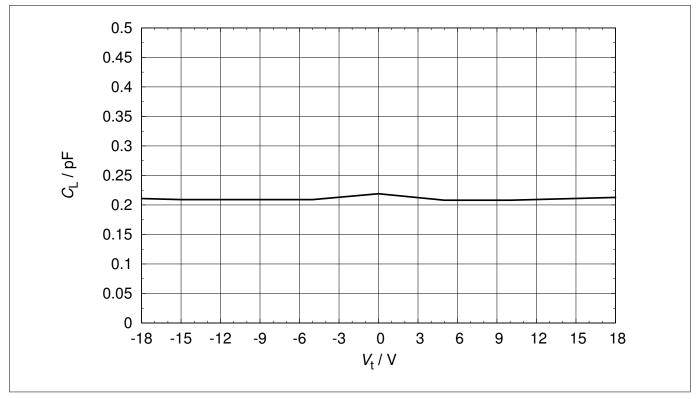


Figure 4 Line capacitance: $C_L = f(V_t), f = 1 \text{ MHz}$



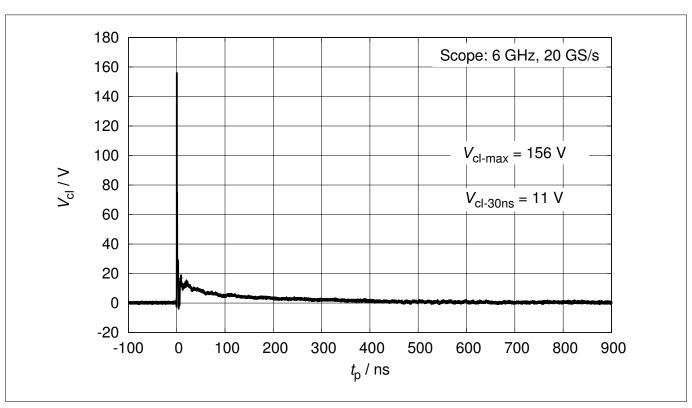


Figure 5 Clamping voltage (ESD): $V_{cl} = f(t_p)$, 8 kV positive pulse according to IEC61000-4-2

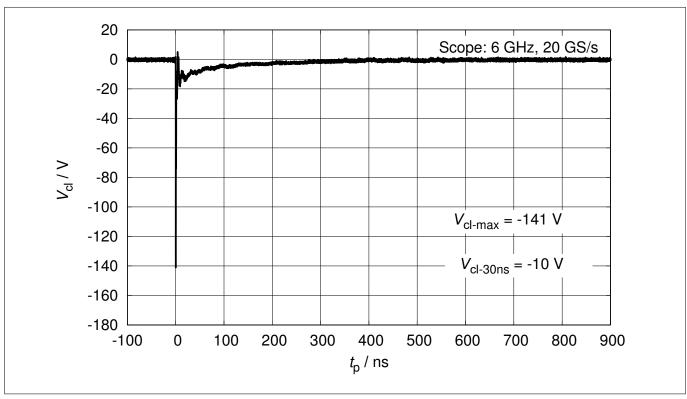


Figure 6 Clamping voltage (ESD): $V_{cl} = f(t_p)$, 8 kV negative pulse according to IEC61000-4-2



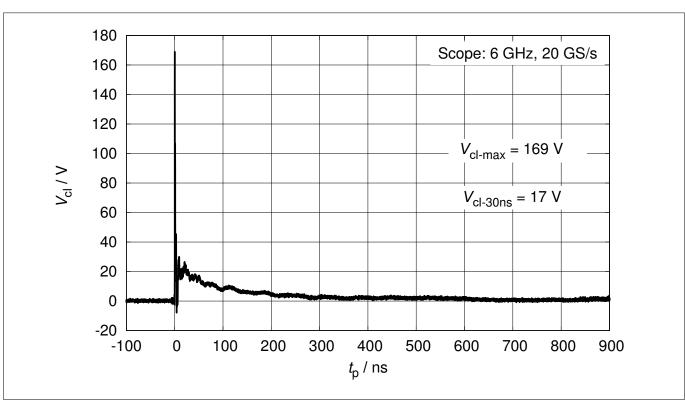


Figure 7 Clamping voltage (ESD): $V_{cl} = f(t_p)$, 15 kV positive pulse according to IEC61000-4-2

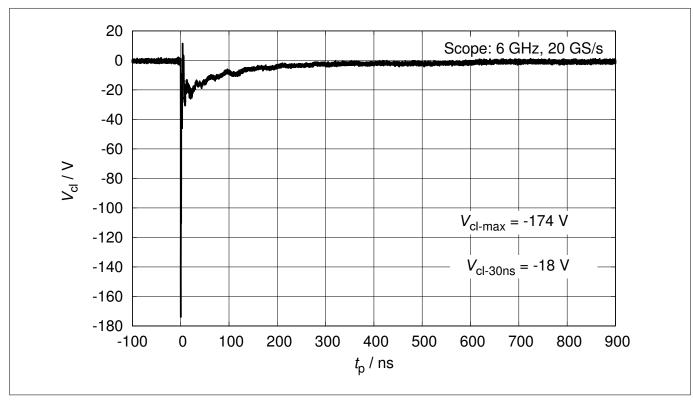


Figure 8 Clamping voltage (ESD): $V_{cl} = f(t_p)$, 15 kV negative pulse according to IEC61000-4-2

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3 Typical characteristic diagrams

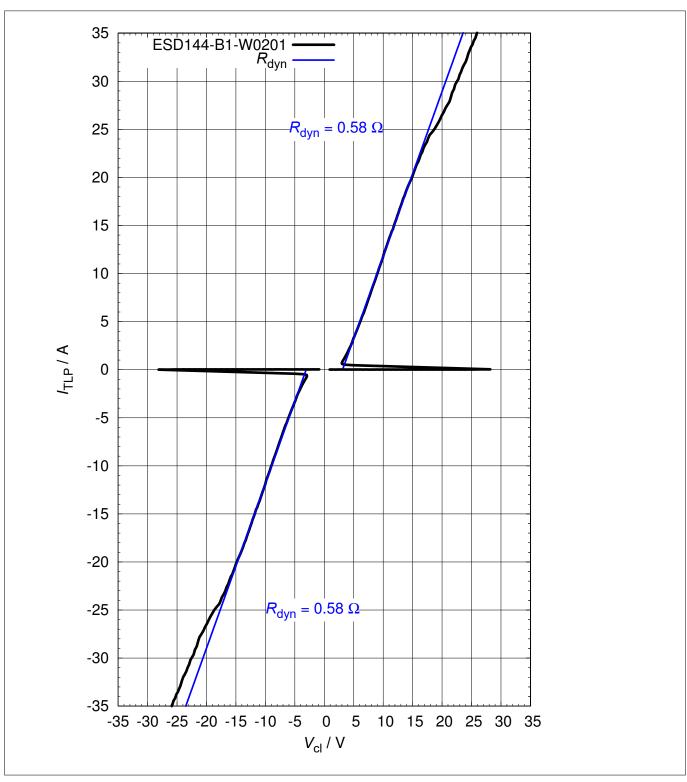


Figure 9 Clamping voltage (TLP): $I_{TLP} = f(V_{cl})$

v2.0



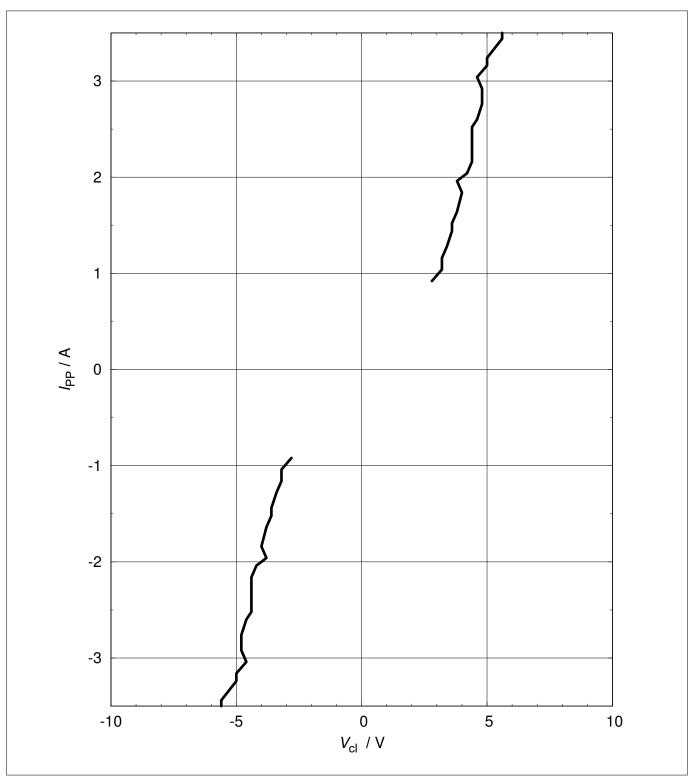


Figure 10 Clamping voltage (Surge): $I_{PP} = f(V_{cl})$ according to IEC61000-4-5

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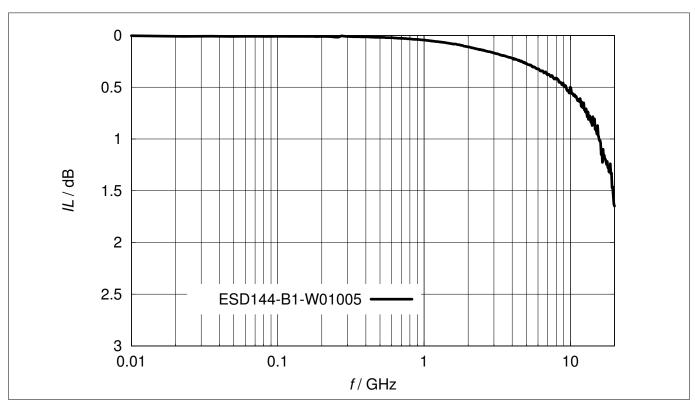


Figure 11 Insertion loss IL = f(f), measured in a 50 Ω system



4 Package information WLL-2-3

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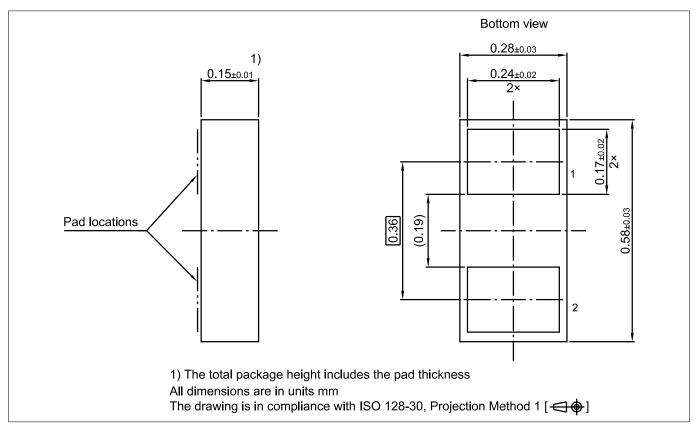


Figure 12 WLL-2-3 package

Note: For package information including footprint, packing and assembly recommendation refer to:

https://www.infineon.com/packages/SG-WLL-2-3/

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5 References

5 References

[1]	Infineon AG - Understanding ESD protection device characteristics
[2]	Infineon AG - Application note AN210 : Effective ESD Protection Design at System Level Using VF-TLP Characterization Methodology

6 Revision history

Document version	Date of release	Description of changes			
1.0	2017-08-14	First final datasheet release			
2.0	2020-11-30	New datasheet layoutEditorial changes			

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